SURFACE MOUNT top hat

RF Transformer

TCM1-1X+

50Ω 1.5 to 500 MHz

FEATURES

- Excellent amplitude unbalance. 0.2 dB typ.
- Excellent phase unbalance, 4 deg. typ. in 1 dB bandwidth
- Plastic base with solder plated leads
- Aqueous washable

Generic photo used for illustration purposes only

CASE STYLE: DB1627

+RoHS Compliant
The +Suffix identifies RoHS Compliance.
See our website for methodologies and qualifications

APPLICATIONS

- Impedance matching
- Balanced to unbalanced transformation
- Push-pull amplifier

ELECTRICAL SPECIFICATIONS AT 25°C

Parameter	Frequency (MHz)	Min.	Typ.	Max.	Units
Impedance Ratio			1		Ohm
Frequency Range		1.5		500	MHz
Insertion Loss*	1.5 - 500		3		dB
	2.5 - 400		2		
	5 - 350		1		

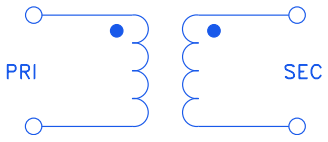
* Insertion Loss is referenced to mid-band loss, 0.9 dB typ.

MAXIMUM RATINGS

Parameter	Ratings
Operating Temperature	-20°C to 85°C
Storage Temperature	-55°C to 100°C
RF Power	0.25 W
DC Current	30 mA

Permanent damage may occur if any of these limits are exceeded.

CONFIGURATION C



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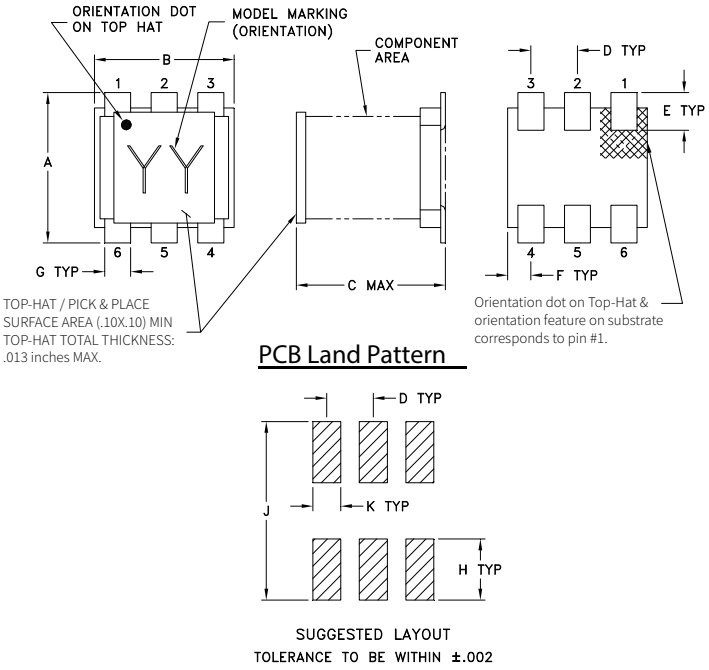
PIN CONNECTIONS

PRIMARY DOT	6
PRIMARY	4
SECONDARY DOT	1
SECONDARY	3
NOT USED	2,5

PRODUCT MARKING: AP

OUTLINE DRAWING



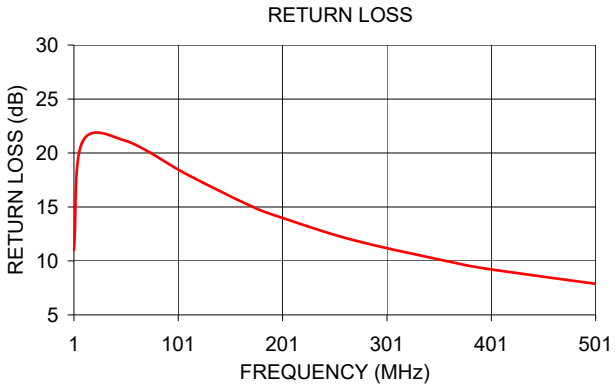
OUTLINE DIMENSIONS (Inches / mm)

A	B	C	D	E	F
.160	.150	.160	.050	.040	.025
4.06	3.81	4.06	1.27	1.02	0.64
G	**H**	**J**	**K**		**wt**
.028	.065	.190	.030		grams
0.71	1.65	4.83	0.76		0.15

TAPE & REEL INFORMATION: F47

TYPICAL PERFORMANCE DATA

Frequency (MHz)	Insertion Loss (dB)	Return Loss (dB)
1.00	1.93	11.00
8.80	0.88	20.96
50.00	0.99	21.15
110.00	1.15	17.98
170.00	1.29	15.11
200.00	1.40	14.01
270.00	1.59	11.90
369.00	1.95	9.77
402.00	2.04	9.20
501.00	2.38	7.88



NOTES

A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.

B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.

C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard. Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html

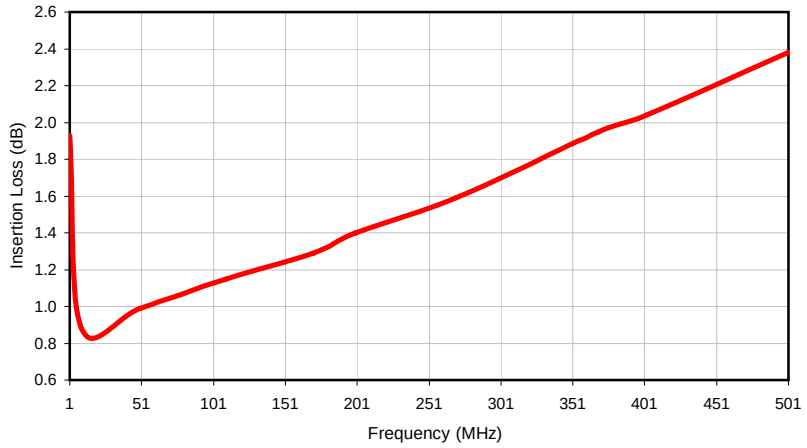
RF Transformer TCM1-1X+

Typical Performance Data

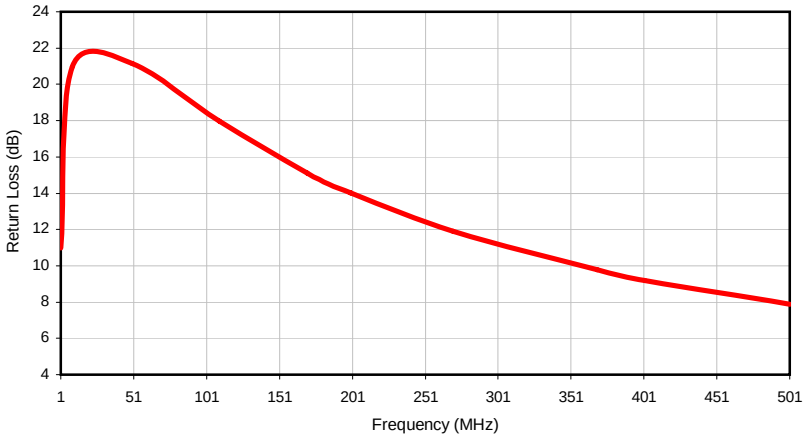
FREQUENCY (MHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)
1.0	1.93	11.00
8.8	0.88	20.96
50.0	0.99	21.15
110.0	1.15	17.98
170.0	1.29	15.11
200.0	1.40	14.01
270.0	1.59	11.90
369.0	1.95	9.77
402.0	2.04	9.20
501.0	2.38	7.88

Typical Performance Data

Insertion Loss



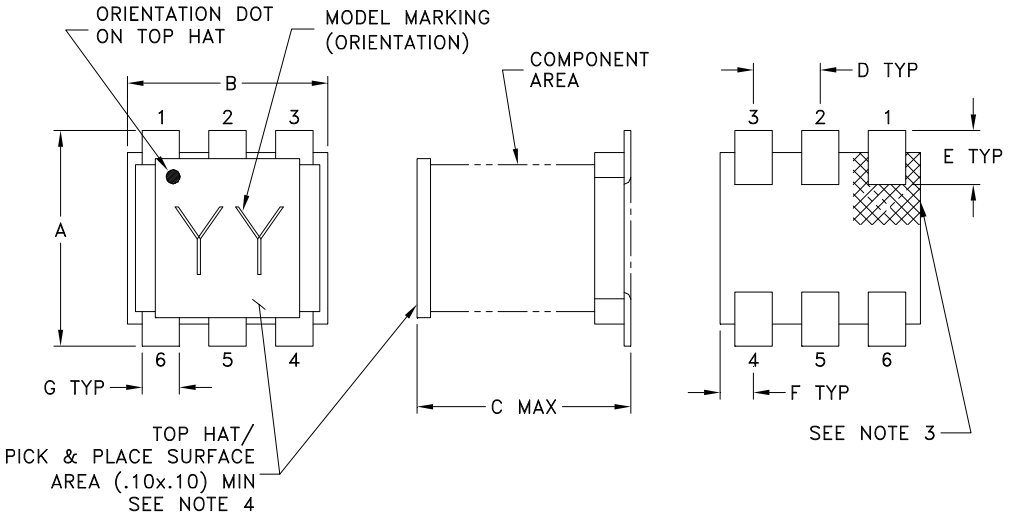
Return Loss



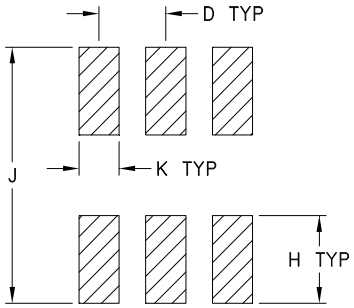
Case Style DB

DB1627

Outline Dimensions



PCB Land Pattern



SUGGESTED LAYOUT
TOLERANCE TO BE WITHIN ±.002

CASE #	A	B	C	D	E	F	G	H	J	K	WT. GRAM
DB1627	.160 (4.06)	.150 (3.81)	.160 (4.06)	.050 (1.27)	.040 (1.02)	.025 (0.64)	.028 (0.71)	.065 (1.65)	.190 (4.83)	.030 (0.76)	.15

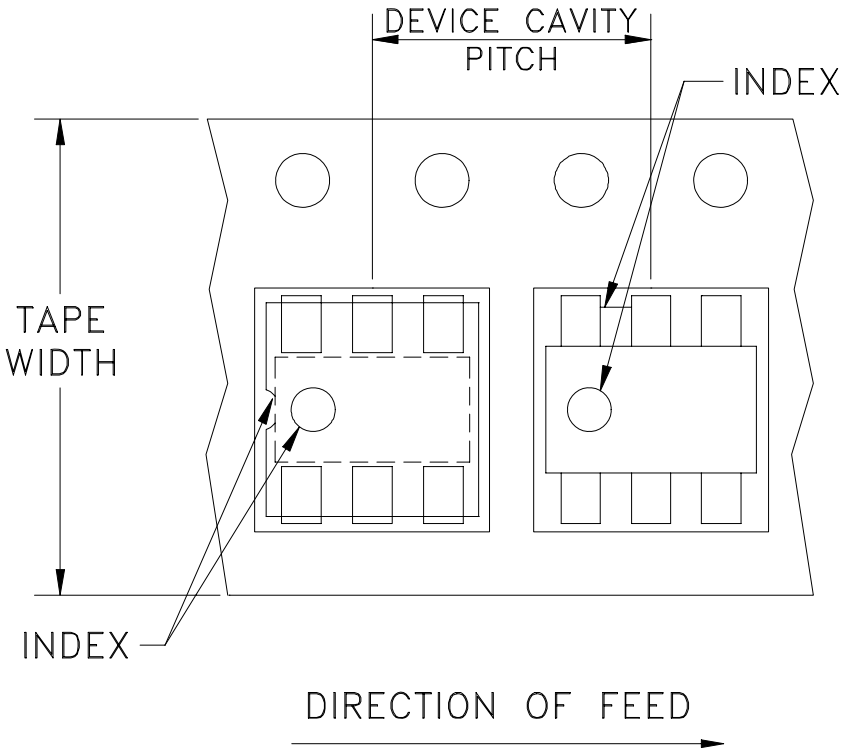
Dimensions are in inches (mm). Tolerances: 2 Pl. ± .01; 3Pl. ± .005

Notes:

1. Case material: Plastic.
2. Termination finish:
   For RoHS Case Styles: Tin plate over Nickel plate. All models, (+) suffix.
   For RoHS-5 Case Styles: Tin-Lead plate. All models, no (+) suffix.
3 Orientation dot on top hat & orientation feature on substrate correspondence to pin #1.
4 Top-Hat total thickness: .013 inches MAX.

Tape & Reel Packaging TR-F47

DEVICE ORIENTATION IN T&R



Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel see note
12	8	13	1000, 2000
		7	20, 50, 100, 200, 500

Note: Please consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf

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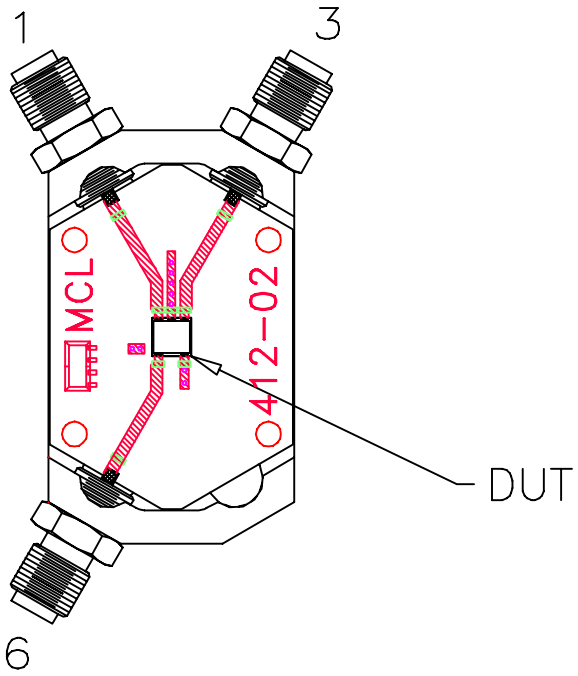
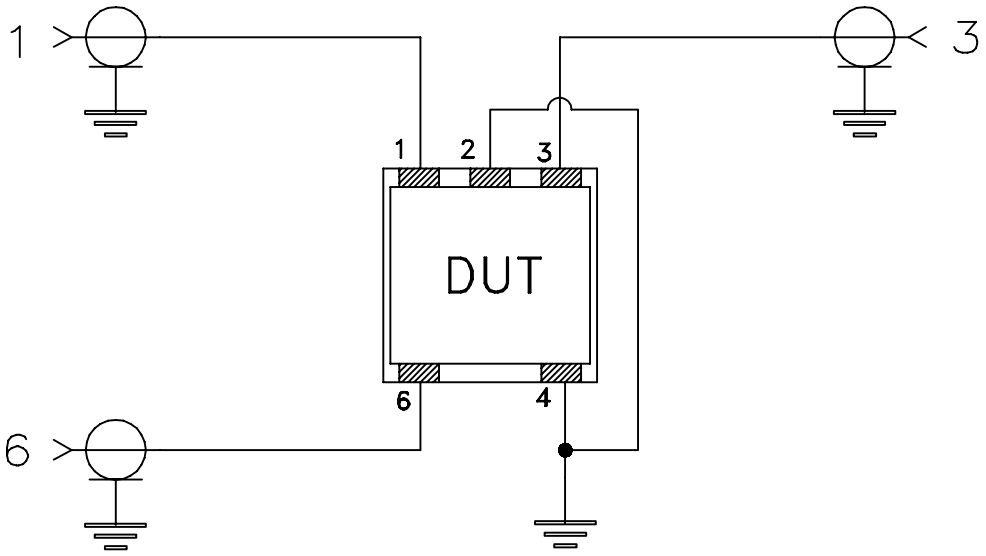
Evaluation Board and Circuit

For Pin Connections refer to Data Sheet of the DUT



TB-145



Schematic Diagram

Notes:

1. 50 Ohm SMA Female connectors.
2. PCB Material: Rogers RO4350B or its equivalent, Dielectric Constant=3.5, Thickness=.020"

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Environmental Specifications ENV02

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-20° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215